SONY CXK582000TM/YM/M -85LL/10LL

262,144-word x 8-bit High-Speed CMOS Static RAM

Description

The CXK582000TM/YM/M is a high-speed CMOS static RAM organized as 262,144-words-by-8-bits.

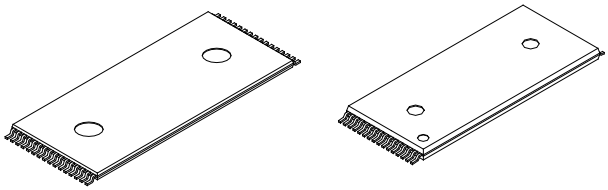
A polysilicon TFT cell technology realized extremely low stand-by current and higher data retention stability.

Special feature are low power consumption and high speed and board package line-up.

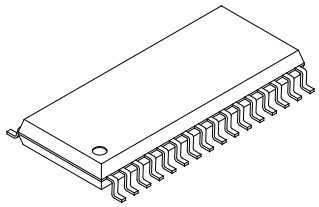
The CXK582000TM/YM/M is a suitable RAM for portable equipment with battery back up.

CXK582000TM
32-pin TSOP (Plastic)

CXK582000YM
32-pin TSOP (Plastic)



CXK582000M
32-pin SOP (Plastic)



Features

- Fast access time: -85LL 85ns (max.)
  -10LL 100ns (max.)
- Low standby current: 40µA (max.)
- Low data retention current: 24µA (max.)
- Single +5V supply: 4.5V to 5.5V
- Low voltage date retention: 2.0V (min.)
- Broad package line-up
  TM/YM 8mm x 20mm, 32-pin TSOP pkg.
  M 525mil, 32-pin SOP pkg.

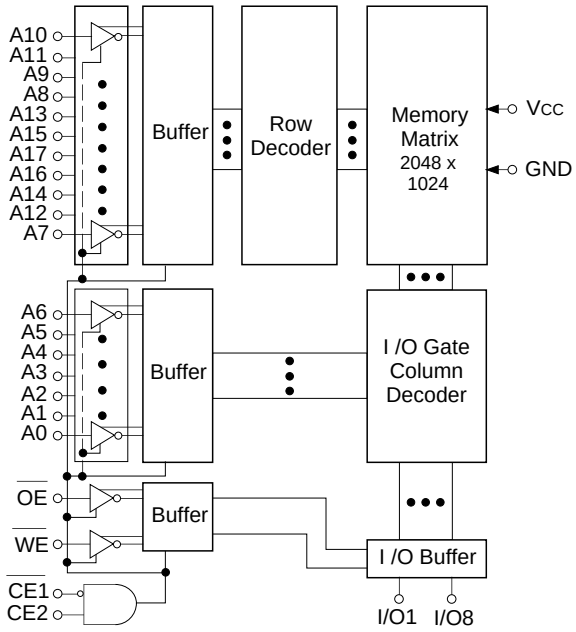
Function

262,144-word x 8-bit static RAM

Structure

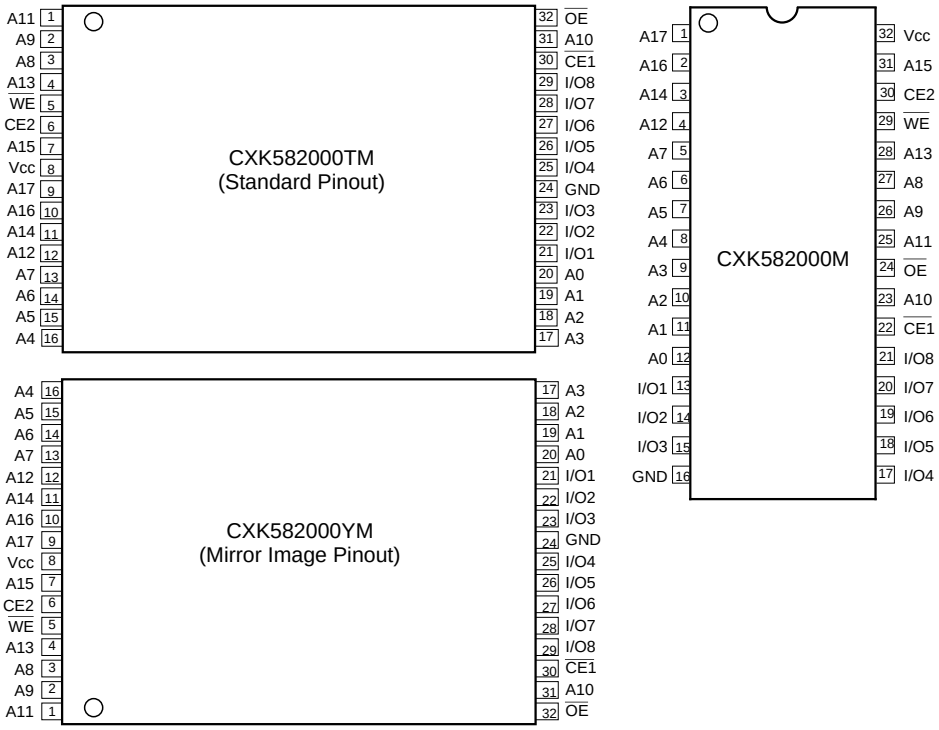
Silicon gate CMOS IC

Block Diagram



E94234–ST

Pin Configuration (Top View)



Pin Description

Symbol	Description
A0 to A17	Address input
I/O1 to I/O8	Data input output
$\overline{CE1}$, CE2	Chip enable 1, 2 input
$\overline{WE}$	Write enable input
$\overline{OE}$	Output enable input
V_{CC}	Power supply
GND	Ground

Absolute Maximum Ratings (Ta = +25°C, GND=0V)

Item	Symbol	Rating	Unit
Supply voltage	V_{CC}	–0.5 to +7.0	V
Input voltage	V_{IN}	–0.5* to V_{CC}+0.5	V
Input and output voltage	$V_{I/O}$	–0.5* to V_{CC}+0.5	V
Allowable power dissipation	P_D	0.7	W
Operating temperature	Topr	0 to +70	°C
Storage temperature	Tstg	–55 to +150	°C
Soldering temperrature · time	Tsolder	235 · 10	°C · s

* V_{IN}, $V_{I/O}$ = –3.0V min. for pulse width less than 50ns.

Truth Table

$\overline{CE1}$	CE2	$\overline{OE}$	$\overline{WE}$	Mode	I/O Pin	V_{CC} Current
H	X	X	X	Not selected	High Z	I_{SB1}, I_{SB2}
X	L	X	X	Not selected	High Z	I_{SB1}, I_{SB2}
L	H	H	H	Output disable	High Z	I_{CC1}, I_{CC2}, I_{CC3}
L	H	L	H	Read	Data out	I_{CC1}, I_{CC2}, I_{CC3}
L	H	X	L	Write	Data in	I_{CC1}, I_{CC2}, I_{CC3}

X: "H" or "L"

DC Recommended Operating Conditions (Ta = 0 to +70°C, GND = 0V)

Item	Symbol	Min.	Typ.	Max.	Unit
Supply voltage	V_{CC}	4.5	5.0	5.5	V
Input high voltage	V_{IH}	2.2	—	V_{CC}+0.3	V
Input low voltage	V_{IL}	–0.3*	—	0.8	V

* V_{IL} = –3.0V min. for pulse width less than 50ns.

Electrical Characteristics

· **DC Characteristics** (V_{CC} = 5V ± 10%, GND = 0V, Ta = 0 to +70°C)

Item	System	Test Conditions		Min.	Typ.*	Max.	Unit
Input leakage current	I_{LI}	V_{IN} = GND to V_{CC}		–1	—	+1	µA
Output leakage current	I_{LO}	$\overline{CE1}$ = V_{IH} or CE2 = V_{IL} or $\overline{OE}$ = V_{IH} or $\overline{WE}$ = V_{IL} $V_{I/O}$ = GND to V_{CC}		–1	—	+1	µA
Operating power supply current	I_{CC1}	$\overline{CE1}$ = V_{IL}, CE2 = V_{IH} V_{IN} = V_{IH} or V_{IL} I_{OUT} = 0mA		—	7	15	mA
Average operating current	I_{CC2}	Min. cycle duty = 100% I_{OUT} = 0mA	-85LL	—	45	80	mA
			-10LL	—	40	70	
	I_{CC3}	Cycle time 1µs duty = 100% I_{OUT} = 0mA $\overline{CE1}$ ≤ 0.2V CE2 ≥ Vcc – 0.2V V_{IL} ≤ 0.2V V_{IH} ≥ Vcc – 0.2V		—	12	24	mA
Standby current	I_{SB1}	CE2 ≤ 0.2V or $\overline{CE1}$ ≥ Vcc–0.2V CE2 ≥ Vcc–0.2V	0 to +70°C	—	—	40	µA
			0 to +40°C	—	—	8	
			+25°C	—	1.4	4	
	I_{SB2}	$\overline{CE1}$ = V_{IH} or CE2 = V_{IL}		—	0.6	3	mA
Output high voltage	V_{OH}	I_{OH} = –1.0mA		2.4	—	—	V
Output low voltage	V_{OL}	I_{OL} = 2.1mA		—	—	0.4	V

* V_{CC} = 5V, Ta = +25°C

I/O Capacitance (Ta = +25°C, f = 1MHz)

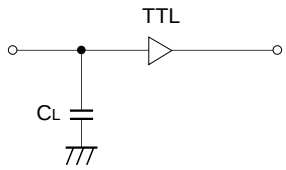
Item	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Input capacitance	C_{IN}	V_{IN}=0V	–	–	7	pF
I/O capacitance	$C_{I/O}$	$V_{I/O}$=0V	–	–	8	pF

N o t e) This parameter is sampled and is not

AC Characteristics

- **AC Test Conditions** (V_{CC}=5V±10%, Ta=0 to +70°C)

Item	Conditions
Input pulse high level	V_{IH} = 2.2V
Input pulse low level	V_{IL} = 0.8V
Input rise time	tr = 5ns
Input fall time	tf = 5ns
Input and output reference level	1.5V
Output load conditions	C_L* = 100pF, 1TTL



*C_L includes scope and jig capacitances.

• **Read Cycle** ($\overline{WE}$ = "H") (Ta = 0 to +70°C)

Item	Symbol	-85LL		-10LL		Unit
		Min.	Max.	Min.	Max.	
Read cycle time	t_{RC}	85	–	100	–	ns
Address access time	t_{AA}	–	85	–	100	ns
Chip enable access time ($\overline{CE1}$)	t_{CO1}	–	85	–	100	ns
Chip enable access time (CE2)	t_{CO2}	–	85	–	100	ns
Output enable to output valid	t_{OE}	–	45	–	50	ns
Output hold from address change	t_{OH}	15	–	15	–	ns
Chip enable to output in low Z ($\overline{CE1}$, CE2)	t_{LZ1}, t_{LZ2}	10	–	10	–	ns
Output enable to output in low Z ($\overline{OE}$)	t_{OLZ}	5	–	5	–	ns
Chip disable to output in high Z ($\overline{CE1}$, CE2)	t_{HZ1}, t_{HZ2}*	–	25	–	35	ns
Output disable to output in high Z ($\overline{OE}$)	t_{OHZ}*	–	25	–	35	ns

* t_{HZ1}, t_{HZ2} and t_{OHZ} are defined as the time required for outputs to turn to high impedance state and are not referred to as output voltage levels.

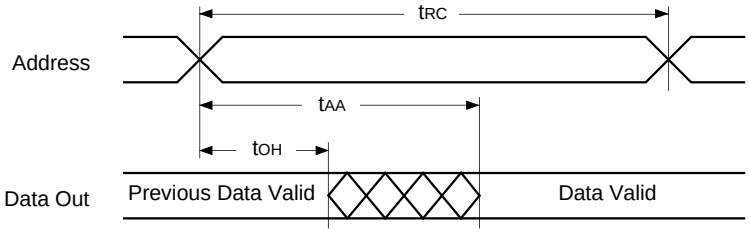
• **Write Cycle** (Ta = 0 to +70°C)

Item	Symbol	-85LL		-10LL		Unit
		Min.	Max.	Min.	Max.	
Write cycle time	t_{WC}	85	–	100	–	ns
Address valid to end of write	t_{AW}	65	–	70	–	ns
Chip enable to end of write	t_{CW}	65	–	70	–	ns
Data to write time overlap	t_{DW}	35	–	45	–	ns
Data hold from write time	t_{DH}	0	–	0	–	ns
Write pulse width	t_{WP}	60	–	70	–	ns
Address setup time	t_{AS}	0	–	0	–	ns
Write recovery time ($\overline{WE}$)	t_{WR}	5	–	5	–	ns
Write recovery time ($\overline{CE1}$, CE2)	t_{WR1}	5	–	5	–	ns
Output active from end of write	t_{OW}	10	–	10	–	ns
Write to output in high Z	t_{WHZ}*	–	25	–	30	ns

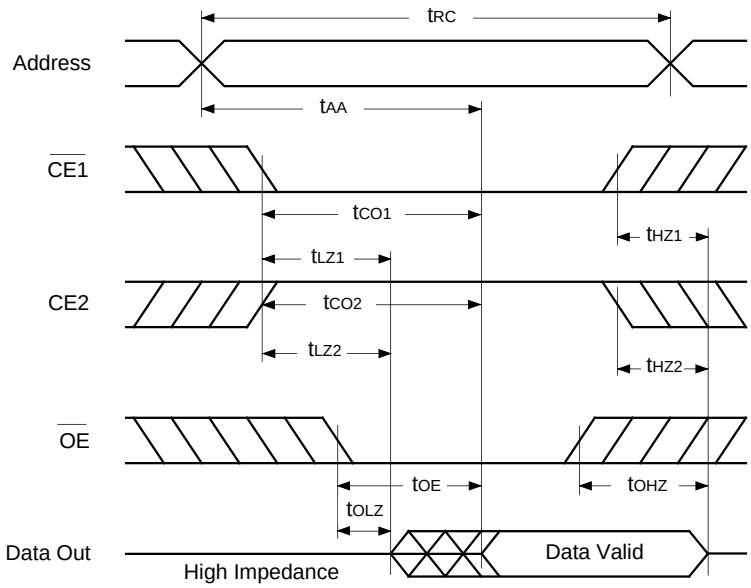
* t_{WHZ} is defined as the time required for outputs to turn to high impedance state and is not referred to as output voltage level.

Timing Waveform

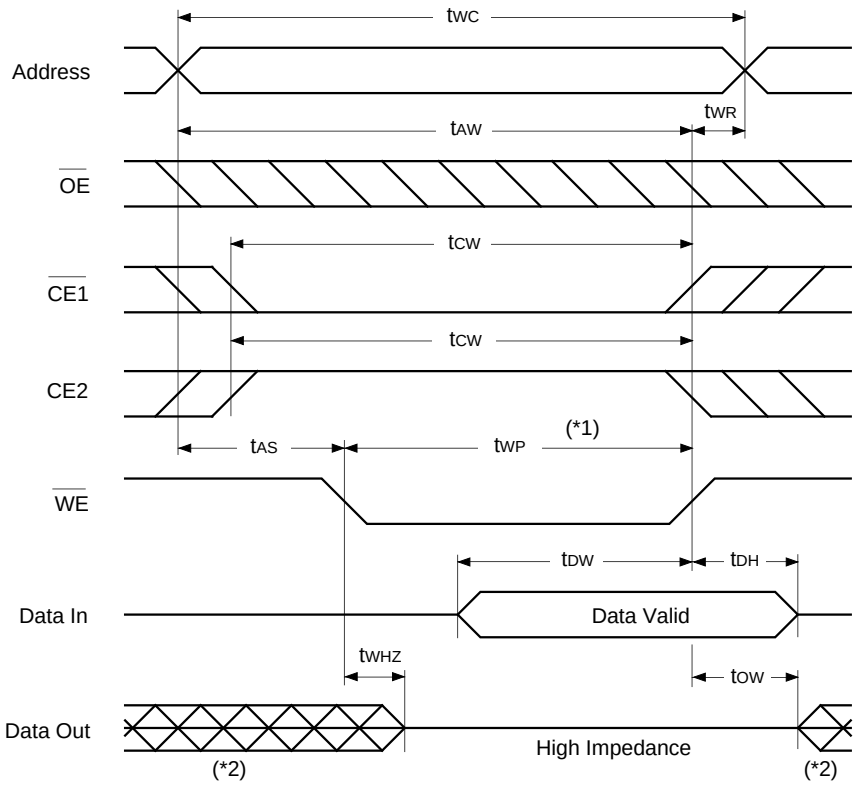
- Read Cycle (1) : $\overline{CE1}$ = $\overline{OE}$ = V_{IL}, CE2 = V_{IH}, $\overline{WE}$ = V_{IH}



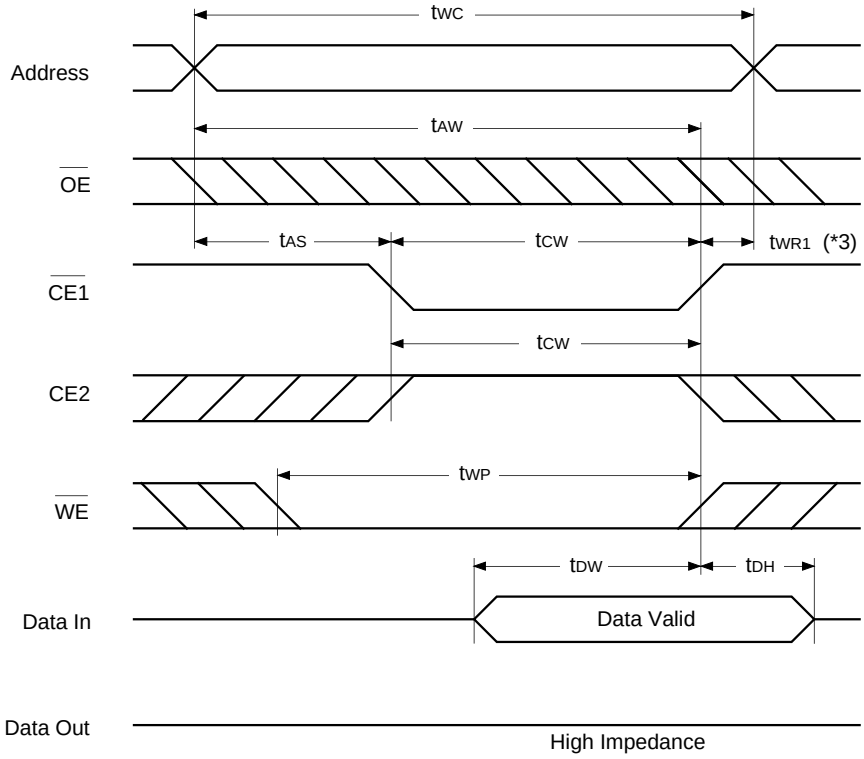
- Read Cycle (2) : $\overline{WE}$ = V_{IH}



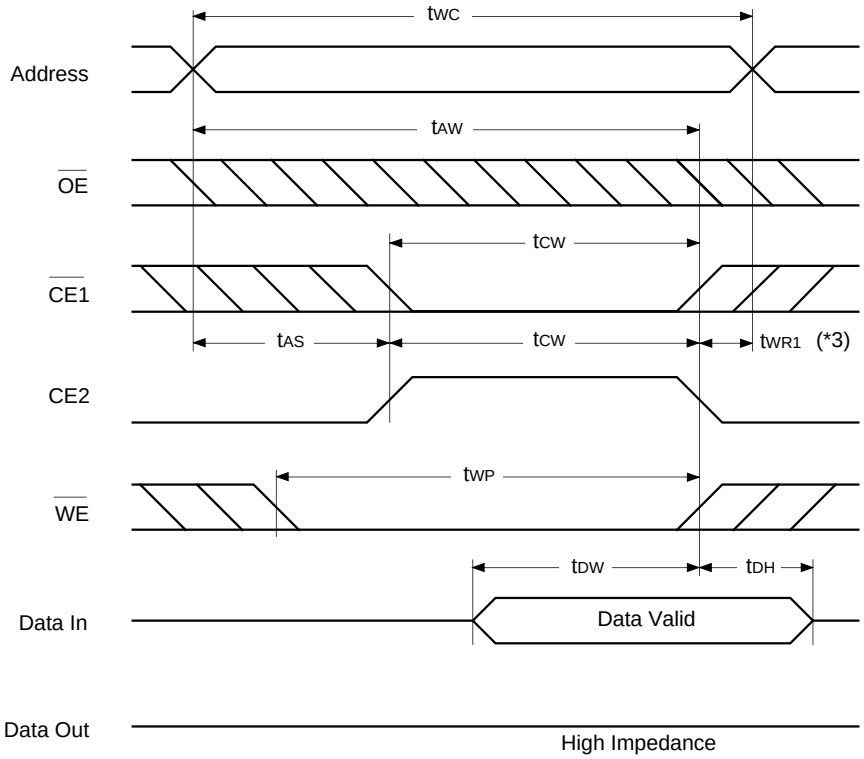
- Write Cycle (1): $\overline{WE}$ Control



- Write Cycle (2): $\overline{CE1}$ Control



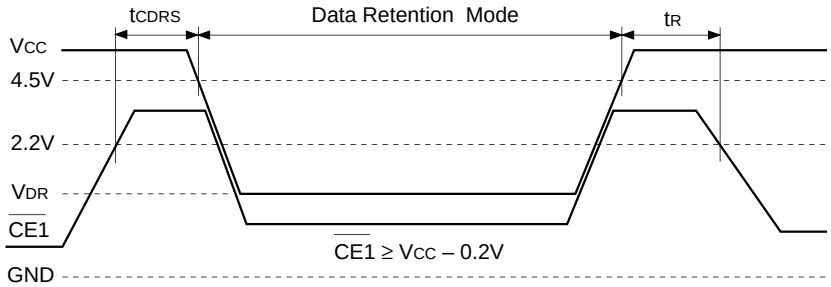
• Write Cycle (3): CE2 Control



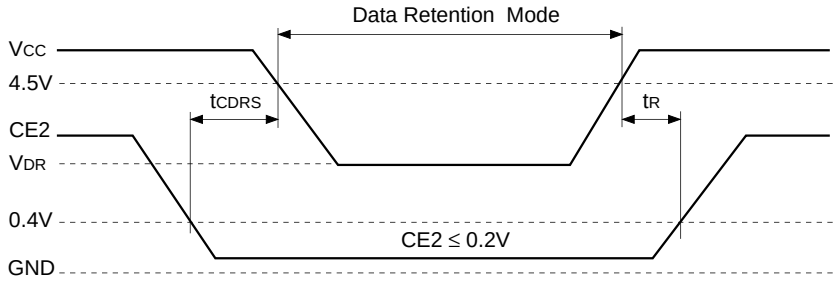
*1 Write is executed when both $\overline{CE1}$ and $\overline{WE}$ are at low and CE2 is at high simultaneously.
*2 Do not apply the data input voltage of the opposite phase to the output while I/O pin is in output condition.
*3 t_{WR1} is tested from either the rising edge of $\overline{CE1}$ or the falling edge of CE2, whichever comes earlier, until the end of the write cycle.

Data Retention Waveform

- Low supply voltage data retention waveform (1) ($\overline{CE1}$ control)



- Low supply voltage data retention waveform (2) (CE2 control)



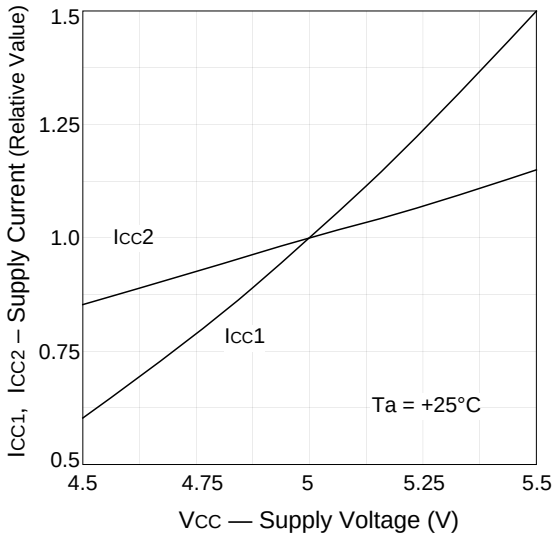
Data Retention Characteristics (Ta = 0 to +70°C)

Item	Symbol	Test Conditions		Min.	Typ.	Max.	Unit
Data retention voltage	V_{DR}	*		2.0	—	5.5	V
Data retention current	I_{CCDR1}	V_{CC} = 3.0V*	0 to +70°C	—	—	24	µA
			0 to +40°C	—	—	4.8	
			+25°C	—	0.8	2.4	
	I_{CCDR2}	V_{CC} = 2.0 to 5.5V*		—	1.4	40	µA
Data retention setup time	t_{CDRS}	Chip disable to data retention mode		0	—	—	ns
Recovery time	t_R			5	—	—	ms

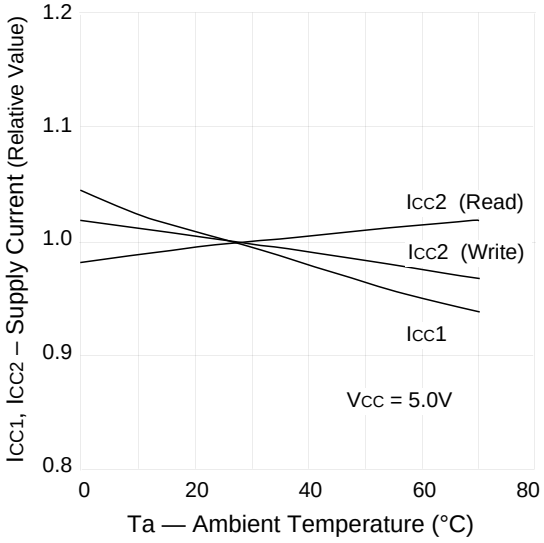
* $\overline{CE1}$ ≥ Vcc – 0.2V, CE2 ≥ Vcc – 0.2V ($\overline{CE1}$ control) or CE2 ≤ 0.2V (CE2 control)

Example of Representative Characteristics

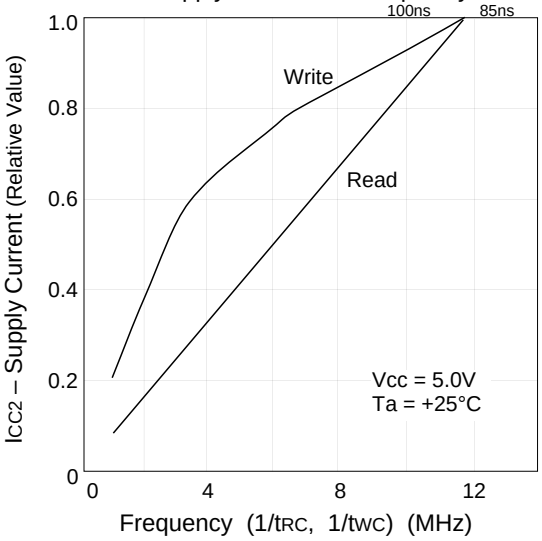
Supply Current vs. Supply Voltage



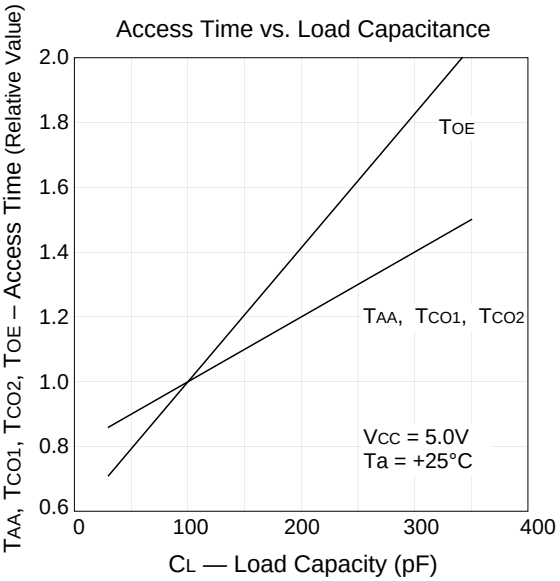
Supply Current vs. Ambient Temperature



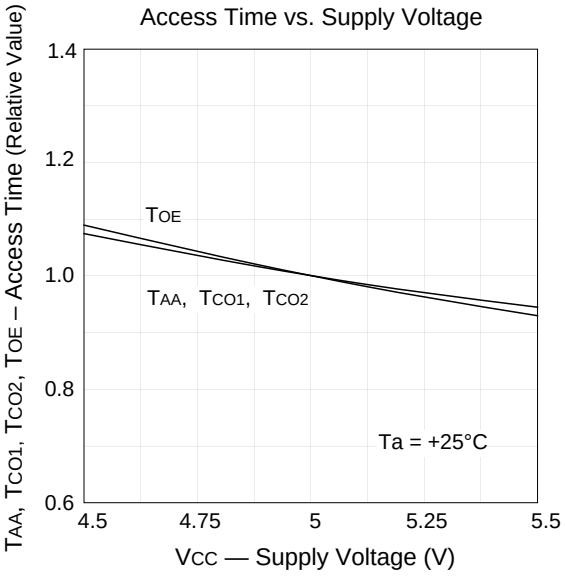
Supply Current vs. Frequency



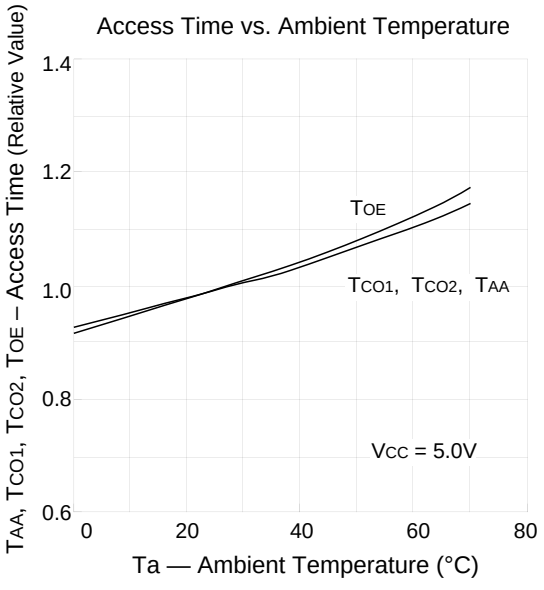
Access Time vs. Load Capacitance



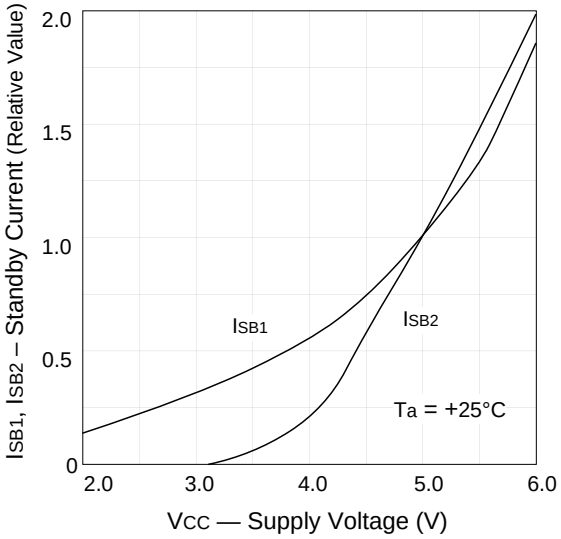
Access Time vs. Supply Voltage



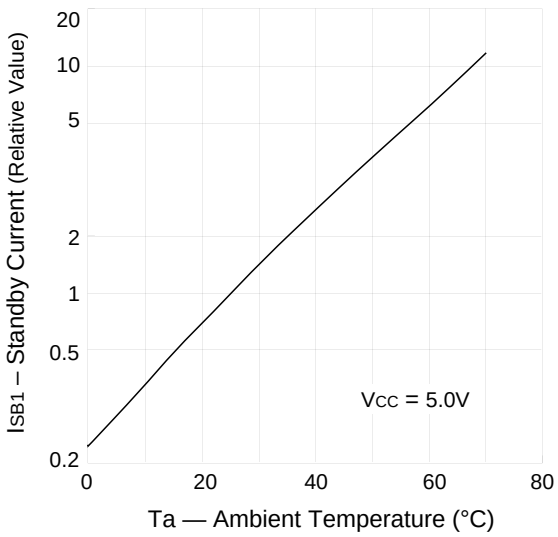
Access Time vs. Ambient Temperature



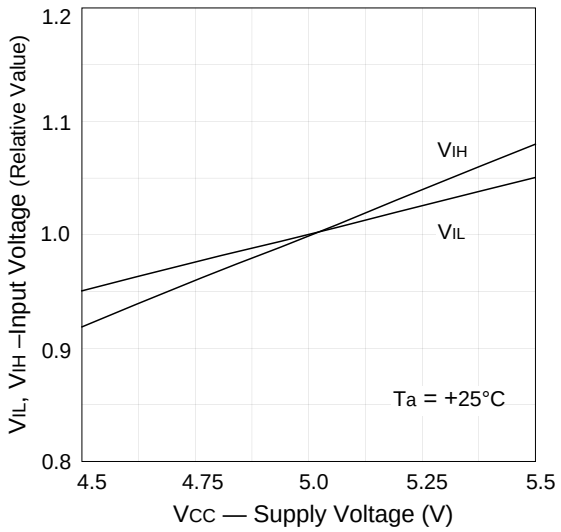
Standby Current vs. Supply Voltage



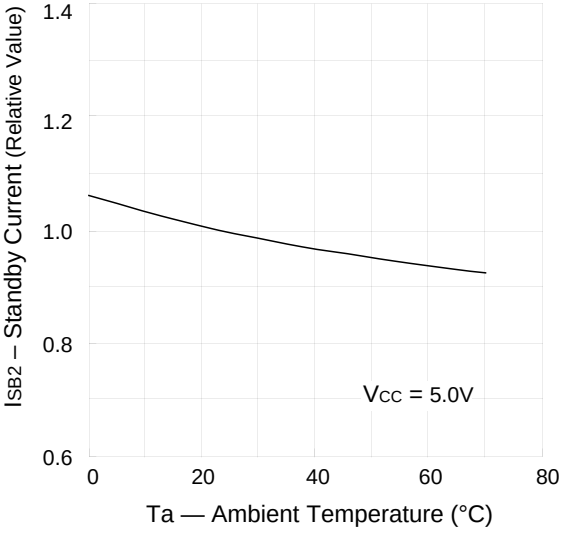
Standby Current vs. Ambient Temperature



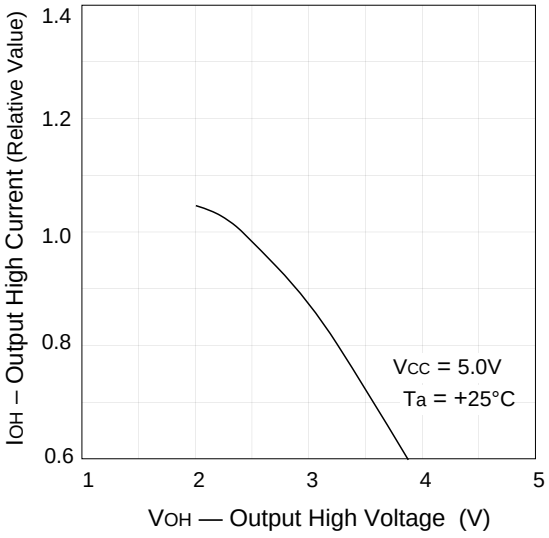
Input Voltage Level vs. Supply Voltage



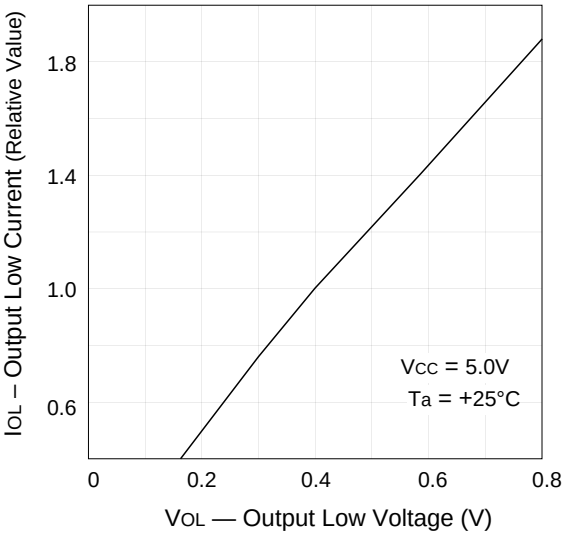
Standby Current vs. Ambient Temperature



Output High Current vs. Output High Voltage



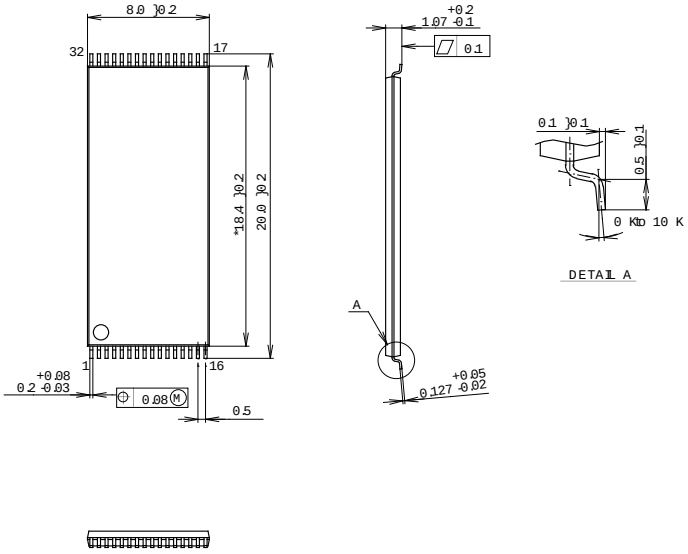
Output Low Current vs. Output Low Voltage



Package Outline Unit : mm

CXK582000TM

32PIN TSOP (I) (PLASTIC)



NOTE : *NOT INCLUDE MOLD FINS.

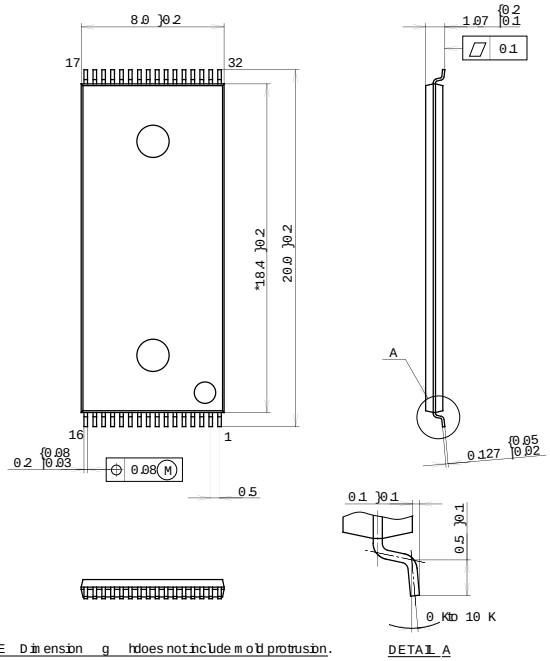
SONY CODE	TSOP-32P-L01
EIAJ CODE	TSOP032-P-0820-A
JEDEC CODE	———

PACKAGE STRUCTURE

MOLDING COMPOUND	EPOXY/PHENOL RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42 ALLOY
PACKAGE WEIGHT	0.3g

CXK582000YM

32PIN TSOP (PLASTIC)



NOTE Dimension g does not include mold protrusion.

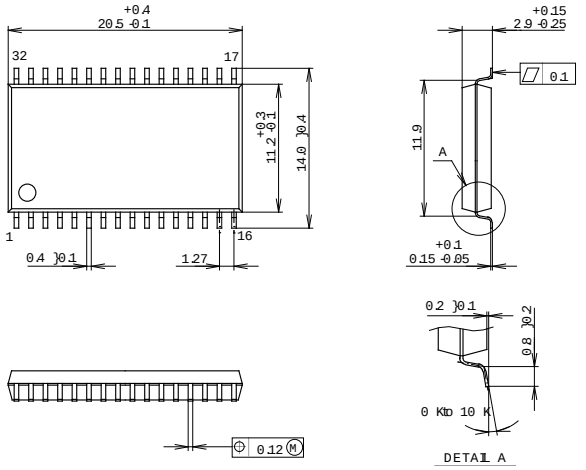
SONY CODE	TSOP-32P-L01R
EIAJ CODE	TSOP032-P-0820-B
JEDEC CODE	———

PACKAGE STRUCTURE

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42 ALLOY
PACKAGE WEIGHT	0.3g

CXK582000M

32PIN SOP(PLASTIC) 525MIL



PACKAGE STRUCTURE

SONY CODE	SOP-32P-L02
EIAJ CODE	*SOP032-P-0525-A
JEDEC CODE	

MOLDING COMPOUND	EPOXY/PHENOL RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42 ALLOY
PACKAGE WEIGHT	1.2